

3D Printing of High Viscosity Reinforced Silicone Elastomers

Nicholas Rodriguez ^{1,2,†}, Samantha Ruelas ^{3,†}, Jean-Baptiste Forien ³, Nikola Dudukovic ¹, Josh DeOtte ¹, Jennifer Rodriguez ³, Bryan Moran ¹, James P. Lewicki ¹, Eric B. Duoss ¹ and James S. Oakdale ^{3,*}

¹ Materials Engineering Division, Lawrence Livermore National Laboratory, 7000 East Avenue, Livermore, CA 94550, USA; nick.rodriguez@utexas.edu (N.R.); dudukovic1@llnl.gov (N.D.); deotte1@llnl.gov (J.D.); moran5@llnl.gov (B.M.); lewicki1@llnl.gov (J.P.L.); duoss1@llnl.gov (E.B.D.)

² Department of Mechanical Engineering, The University of Texas at Austin, 204 E. Dean Keeton Street, Austin, TX 78712, USA

³ Materials Science Division, Lawrence Livermore National Laboratory, 7000 East Avenue, Livermore, CA 94550, USA; ruelas7@llnl.gov (S.R.); forien1@llnl.gov (J.-B.F.); rodriguez96@llnl.gov (J.R.)

* Correspondence: oakdale1@llnl.gov; 925-424-4157.

† N.R. and S.R. contributed equally.

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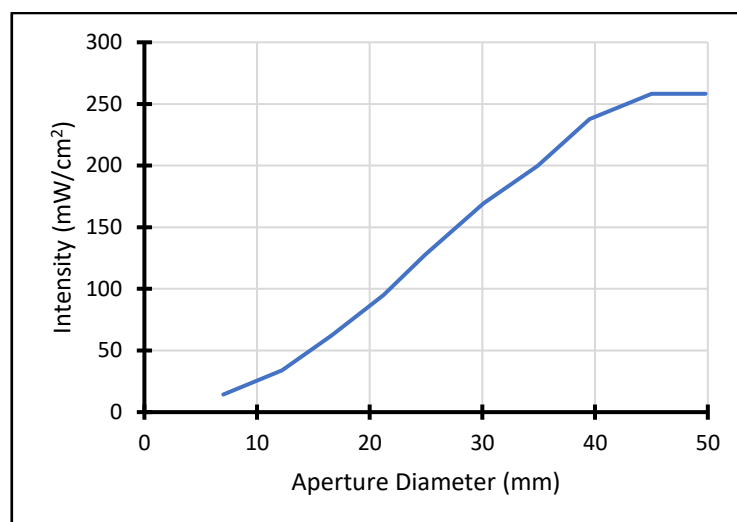


Figure S1. Measured intensity at the build plate as a function of aperture diameter. An aperture diameter of 12.2 mm was used for the curing discussed in this research with a resulting maximum intensity of 34 mW/cm² at the build plane.

Table S1. Solubility of photo-initiator components in TEMQ-1. Compounds were dissolved in 0.25 mL THF and added to 2.5 grams of TEMQ-1 and mixed via planetary centrifugal Thinky mixing. The resulting mixture was left open to the atmosphere to allow the THF to escape and solubility was checked after seven days. A lack of solubility was noted for samples that either turned cloudy or formed a noticeable precipitate.

Reagent	Role	Solubility in PDMS (wt%)
Isopropylthioxanthone (ITX)	Sensitizer	0.15
2-ethylhexyl 4-(dimethylamino)benzoate (EHDA)	Initiator	2.4
2-(2H-benzotriazol-2-yl)-4,6-di-tert-pentylphenol (BTA)	Absorber	0.24
2,5-Bis(5-tert-butyl-benzoxazol-2-yl)thiophene	Absorber	0.003
4-methoxyhydroquinone (MEHQ)	Inhibitor	0.20
Ethyl (2,4,6-trimethylbenzoyl) phenylphosphinate	Initiator	0.12
9,10-diethoxyanthracene	Sensitizer	0.06
Camphorquinone	Sensitizer	1.2

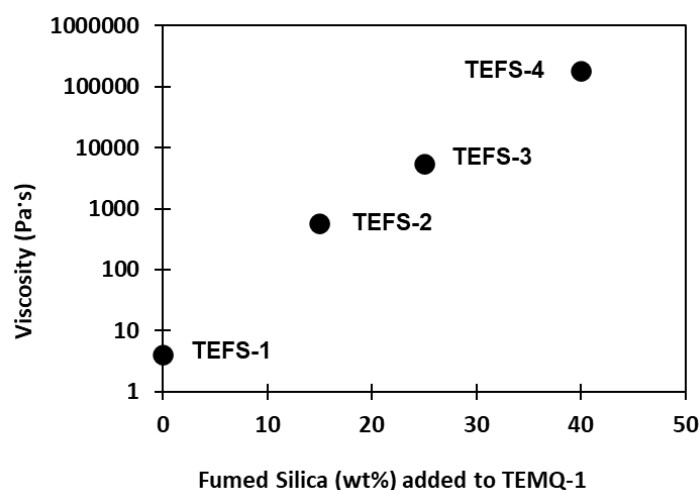


Figure S2. Viscosity of VTS-2 + MFS-1 as a function of silica content. TEMQ-1 = 0 phr. TEMQ-2 = 10 phr. TEMQ-3 = 25 phr. TEMQ-4 = 33 phr.

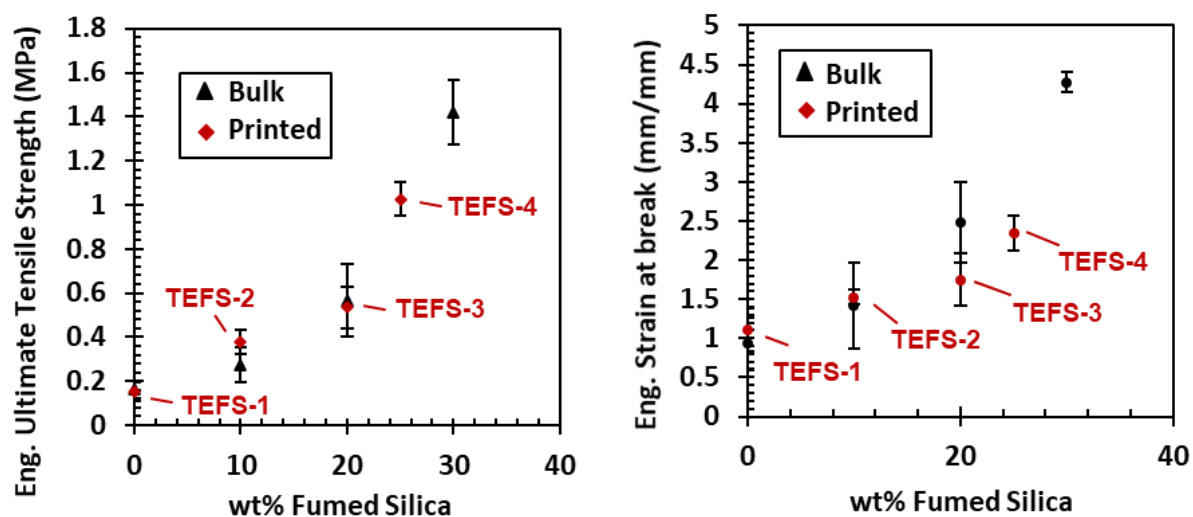


Figure S3. ASTM D638 tensile testing for TEFS-1 through TEFS-4 compared to 'bulk' specimen. TEFS samples were 3D printed (red diamond) in the XY orientation at 405 nm 34 mW/cm². Bulk samples from which ASTM D638 specimen were die-cut, were cast in 3 mm thick sheet and cured under a 405 nm 250 mW/cm² LED flood lamp.

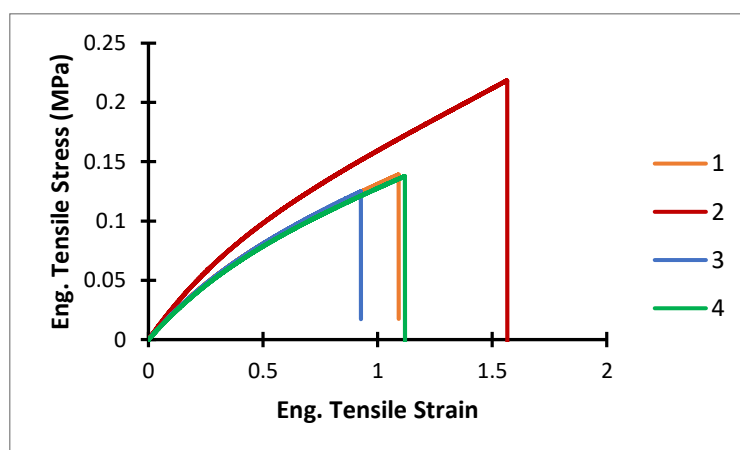


Figure S4. Tensile data for TEFS-1 specimens.

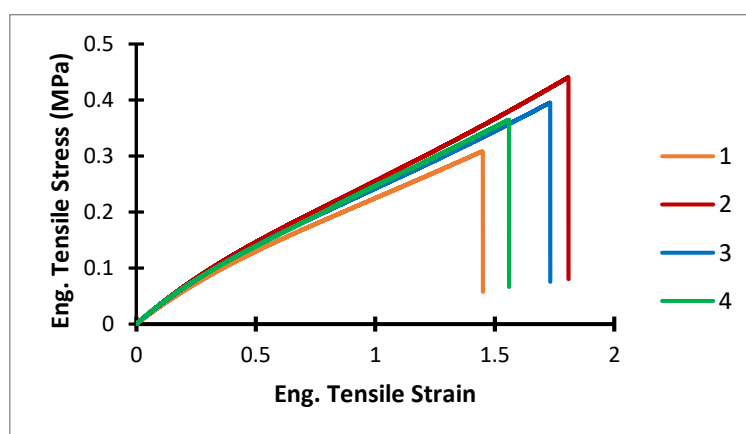


Figure S5. Tensile data for TEFS-2 specimens.

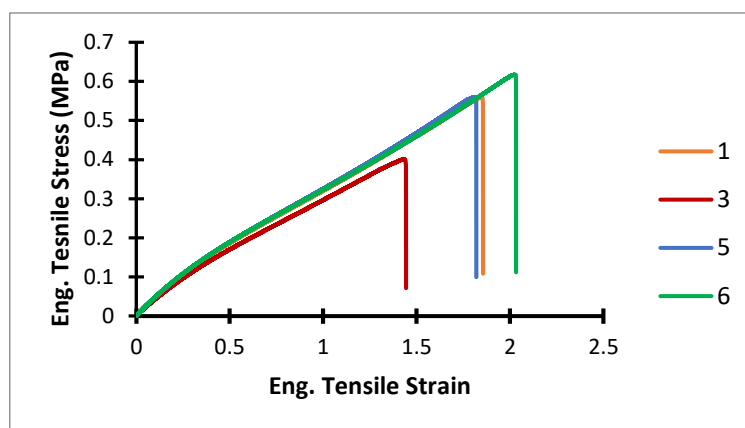


Figure S6. Tensile data for TEFS-3 specimens.

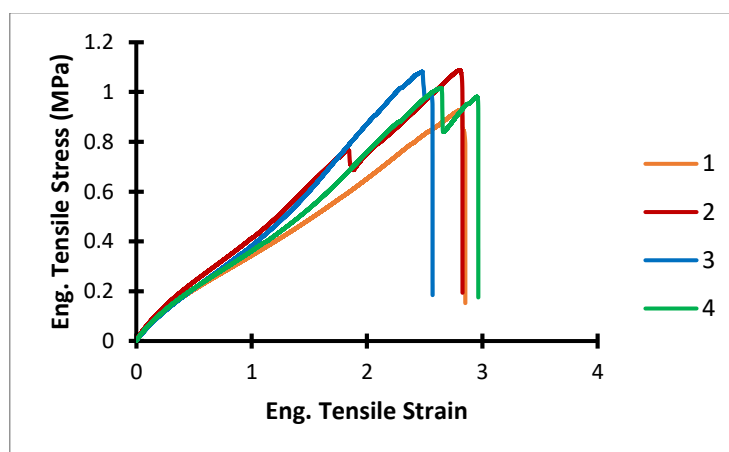


Figure S7. Tensile data for TEFS-4 specimens.

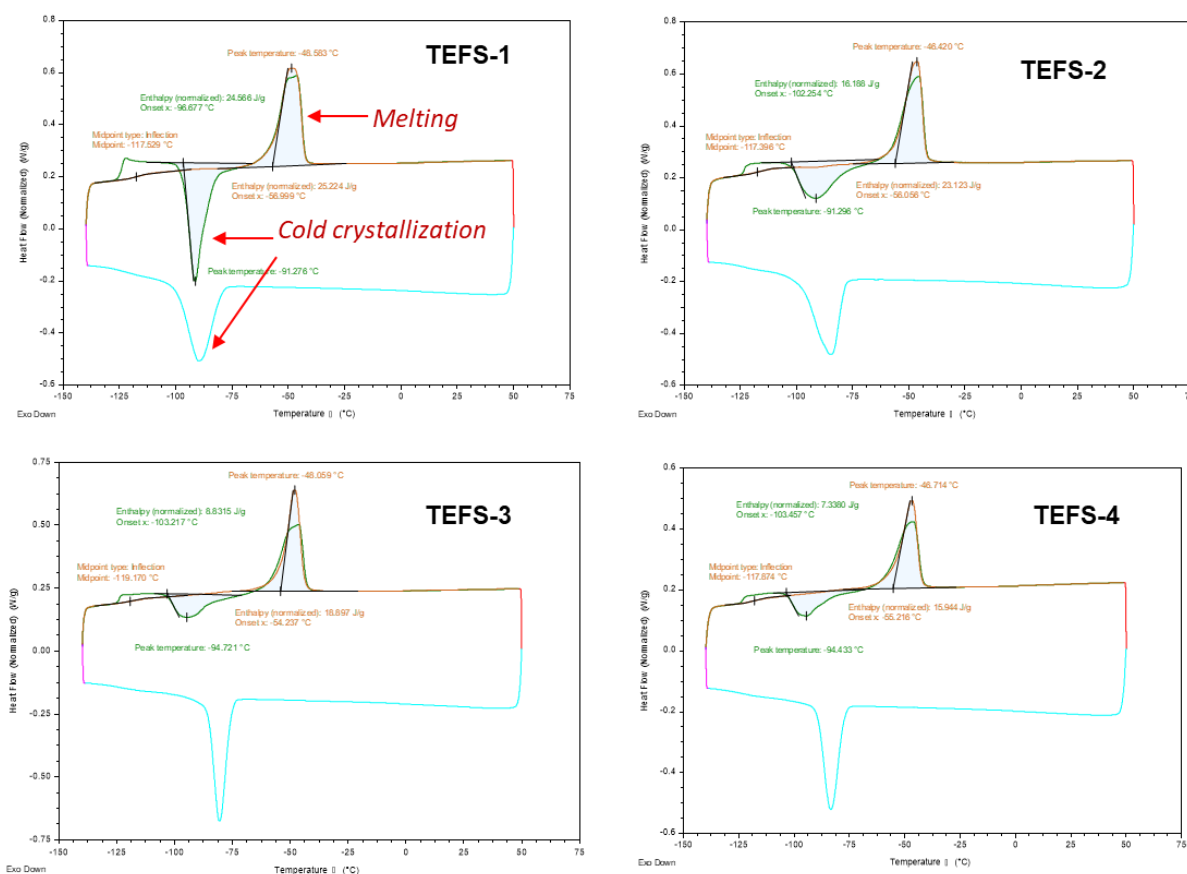


Figure S8. DSC analysis of TEFS1-4. Green trace corresponds to heating from -147 °C to 50 °C at 10 °C per min following quench freezing for one minute. The Light blue trace corresponds to cooling from 50 °C to -147 °C at 10 °C per min. The orange trace corresponds to a final heat through the entire range of temperatures observed.

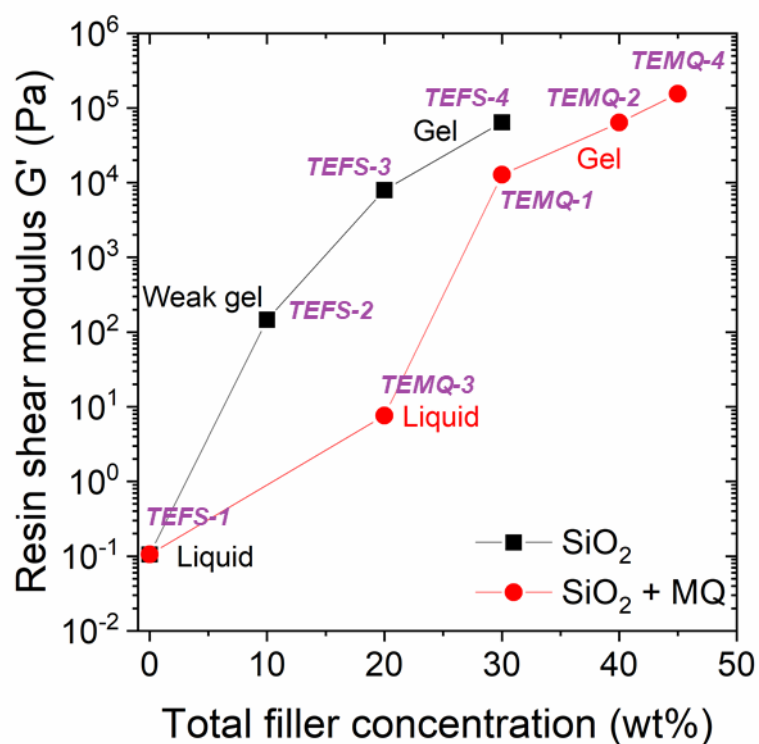


Figure S9. Resin shear modulus as a function of filler concentration (wt%).

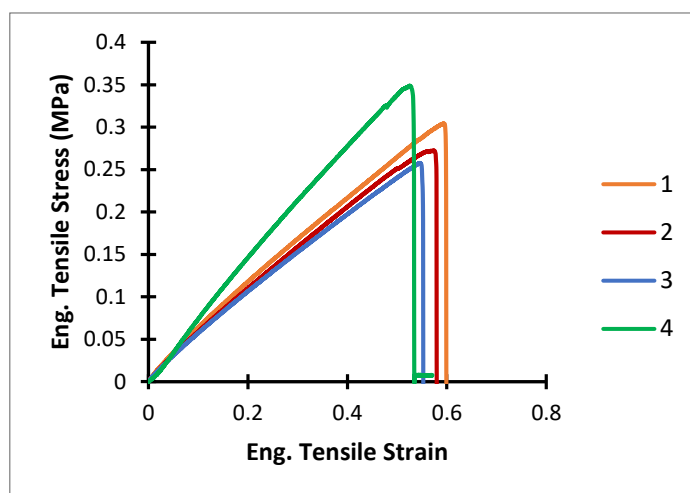


Figure S10. Tensile data for TEFS-5 specimens.

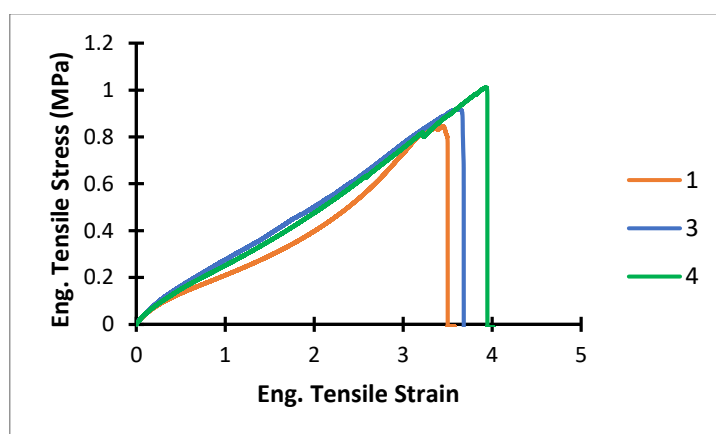


Figure S11. Tensile data for TEFS-6 specimens. Specimen 2 slipped during the course of the experiment—no conclusive data was recorded.

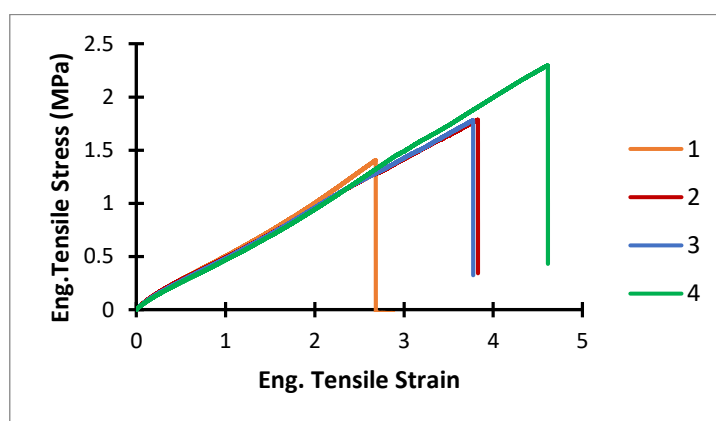


Figure S12. Tensile data for TEMQ-1 specimens.

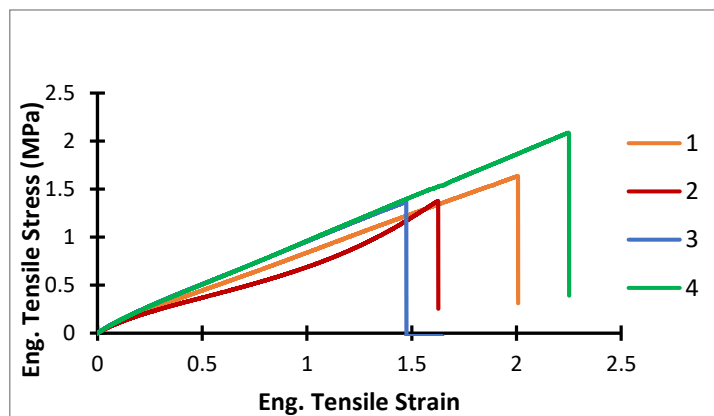


Figure S13. Tensile data for TEMQ-2 specimens.

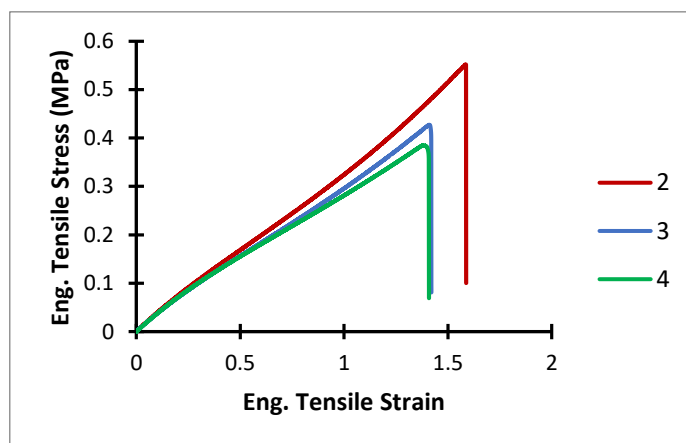


Figure S14. Tensile data for TEMQ-3 specimens. Specimen 1 slipped during the course of the experiment—no conclusive data was recorded.

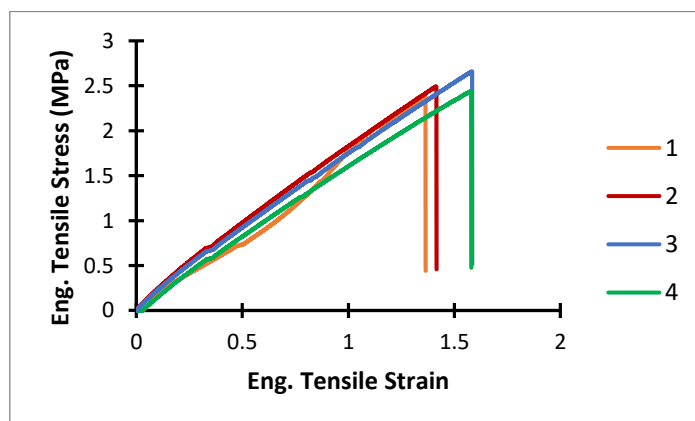


Figure S15. Tensile data for TEMQ-4 specimens.

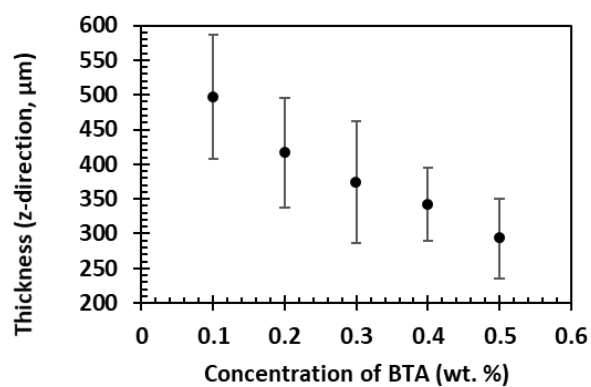


Figure S16. Layer thickness as a function of photo-absorber. BTA concentration was varied in order to decrease layer thickness. Higher concentrations decreased layer thickness by approximately 200 μm .

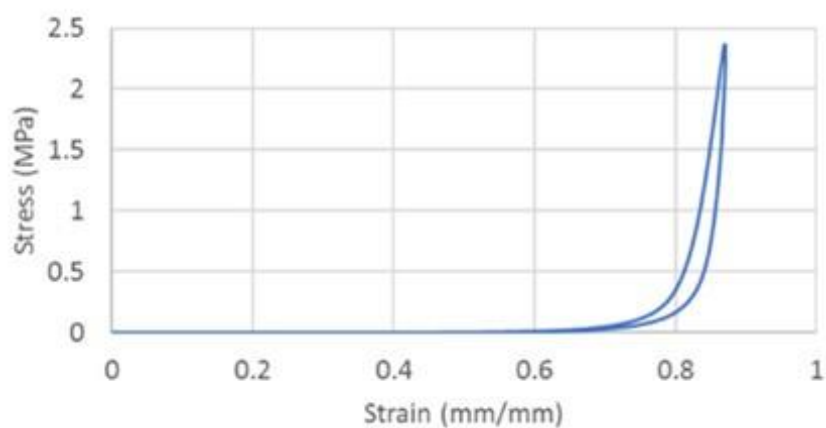


Figure S17. Stress vs strain data for a TEFS-3 octet truss lattice compressed to 87% strain.